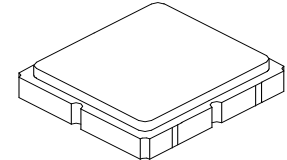


SF2621E

**265.55 MHz
SAW Filter**



SM3030-6

Maximum Ratings:

- Input Power Level: 10 dBm
- DC Voltage : 7.5V
- Operating Temperature: -30°C to +85°C (1)
- Storage Temperature: -40°C to +85°C
- Moisture Sensitivity Level: 1
- AEC-Q200 Qualified

Electrical Characteristics:

Terminating source impedance : $Z_s = 50 \Omega$

Terminating load impedance : $Z_L = 50 \Omega$

Item	Unit	Min.	Typ.(2)	Max.
Center frequency F_o	MHz	-	265.55	-
3dB Bandwidth	kHz	260	550	-
Insertion loss $F_o \pm 100\text{kHz}$	dB	-	3.2	4.0
Ripple $F_o \pm 100\text{kHz}$	dB		0.8	1.2
Group Delay Time Ripple $F_o \pm 100\text{kHz}$	usec		0.5	1.2
Attenuation (reference from 0dB)				
$F_o \pm 600\text{kHz}$	dB	25	30	-
$F_o \pm 1.2\text{MHz}$	dB	40	60	-
$F_o \pm 21.5\text{MHz} \sim F_o \pm 21.7\text{MHz}$	dB	60	63	-
Source impedance Z_s	Ω	-	50	-
Load impedance Z_L	Ω	-	50	-

Notes:

- (1). In production, devices will be tested at room temperature to a guardbanded specification to ensure electrical compliance over temperature.
- (2). Typical values are based on average measurements at room temperature.

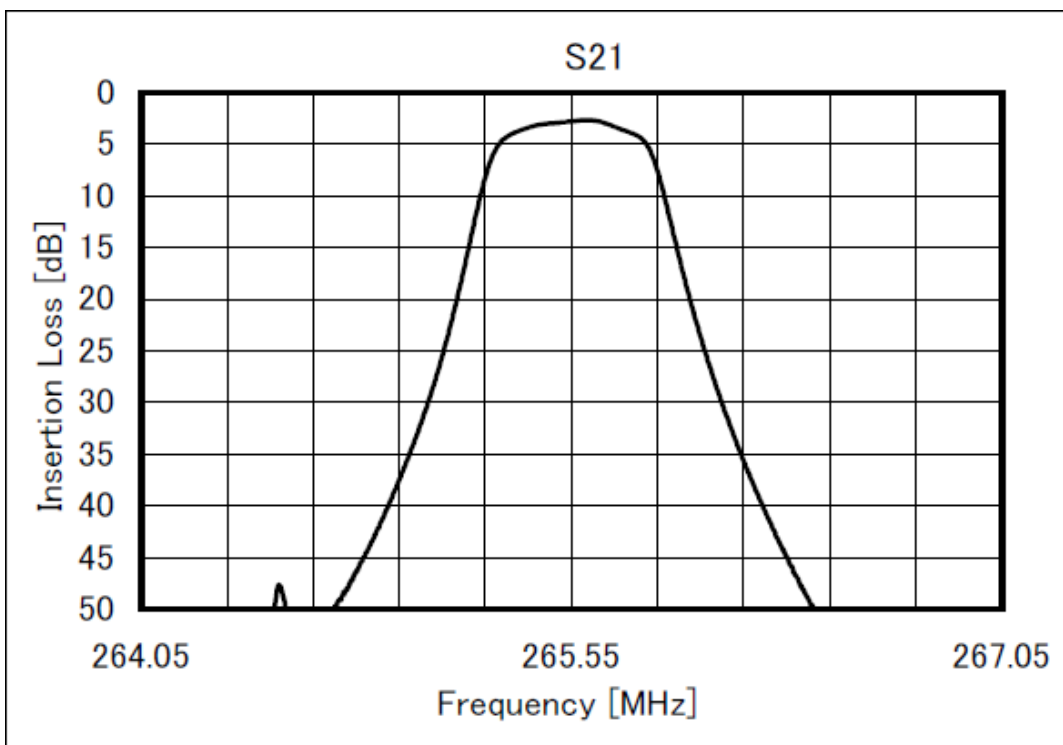


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

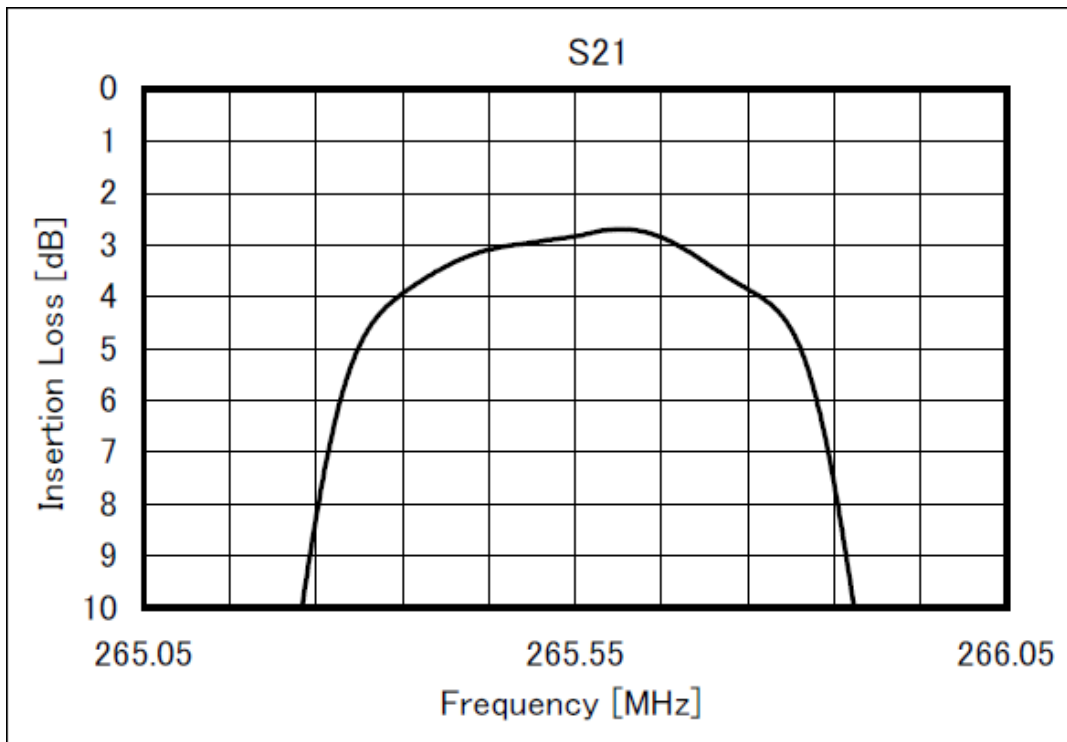
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Frequency Characteristics :(1)

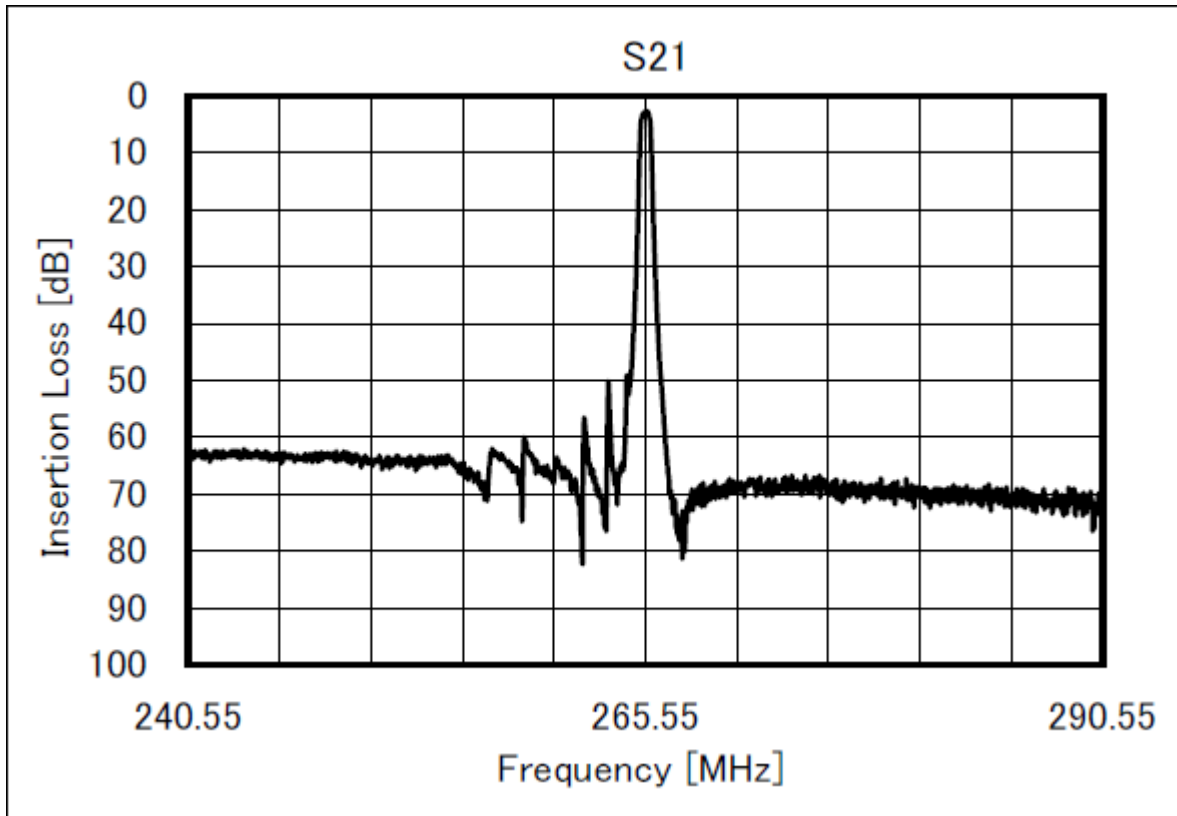
S21 Response: (span 3MHz)



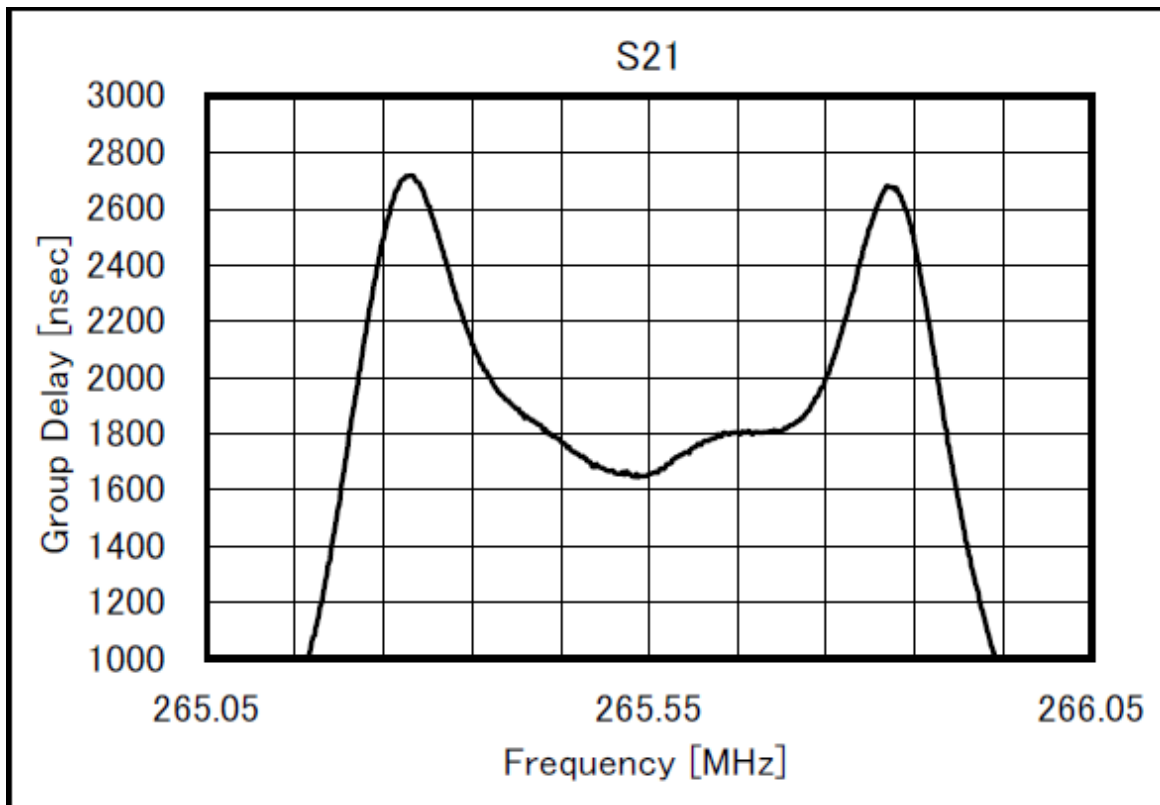
(2) Pass band Response:(span 1MHz)



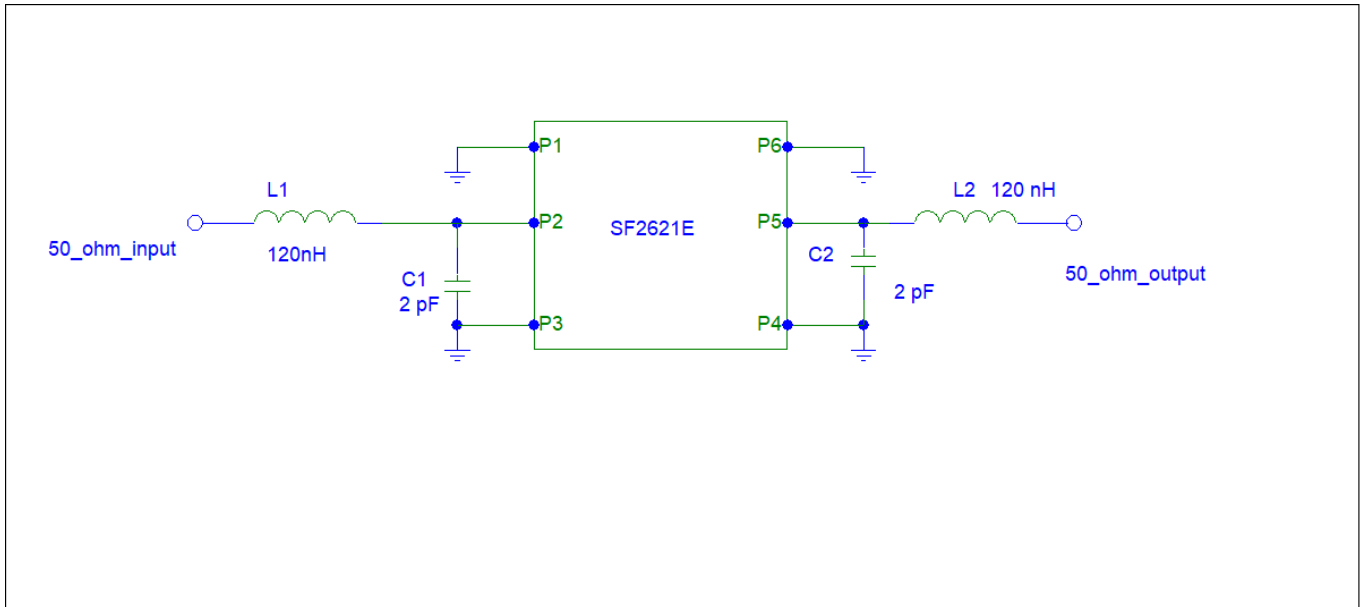
(3) Wide band Response:(span 50MHz)



(4) Group Delay Response: (span 1MHz)

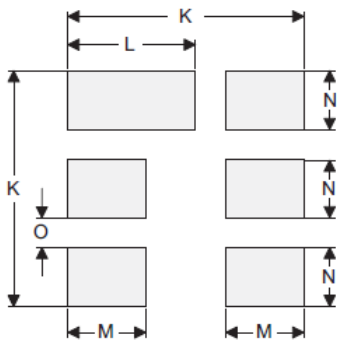
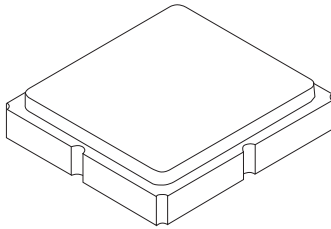


Measurement Circuit:



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



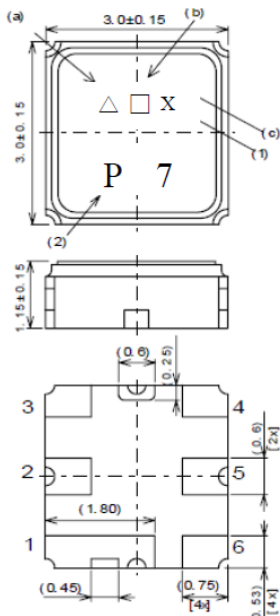
PCB Footprint Top View

Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	



Marking

(1) Lot Number

(a) Year

(b) Month

*Oct... X

Nov... Y

Dec... Z

(c) Date

1-9... 0

10-19... 1

20-31... 2

(2) Part Number Mark

Pin no.	Connection
1	GND
2	IN/OUT
3	GND
4	GND
5	OUT/IN
6	GND

PACKING:

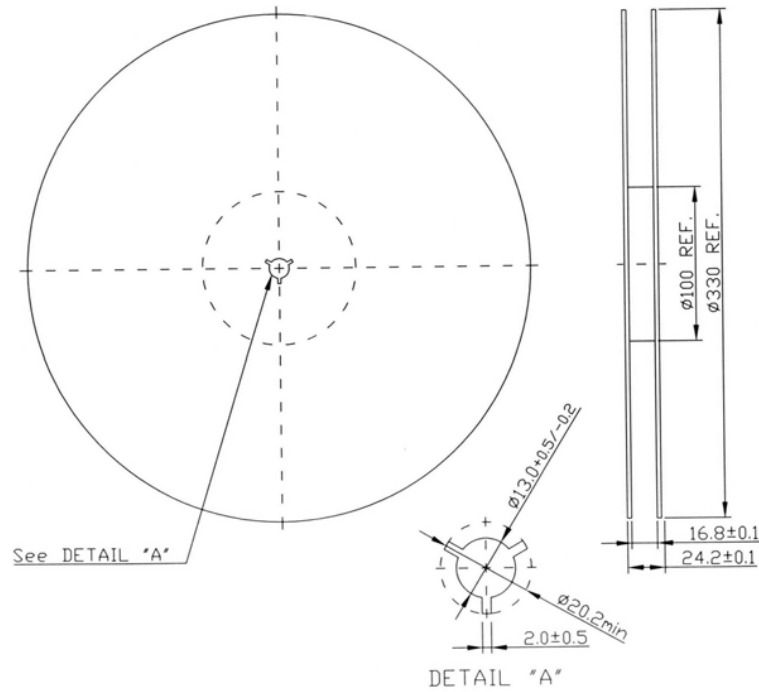
REEL DIMENSION

Tape and Reel Standard per ANSI/EIA-481

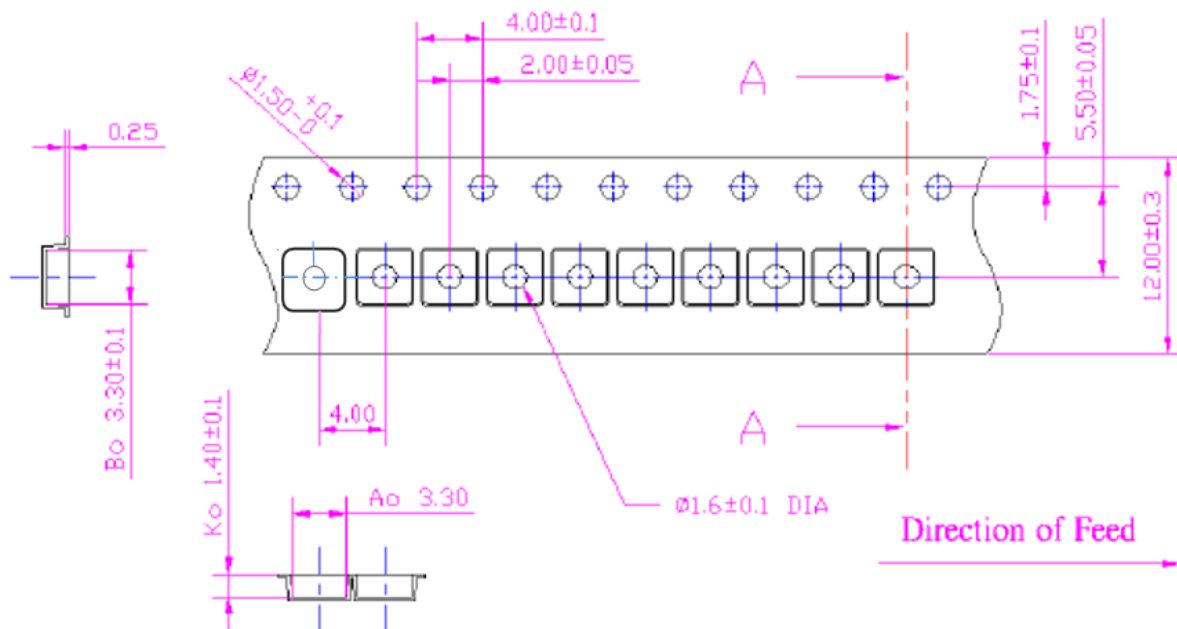
Reel Count:

7" = 500

13" = 3000



Tape Dimensions:



Recommended Solder Profile

